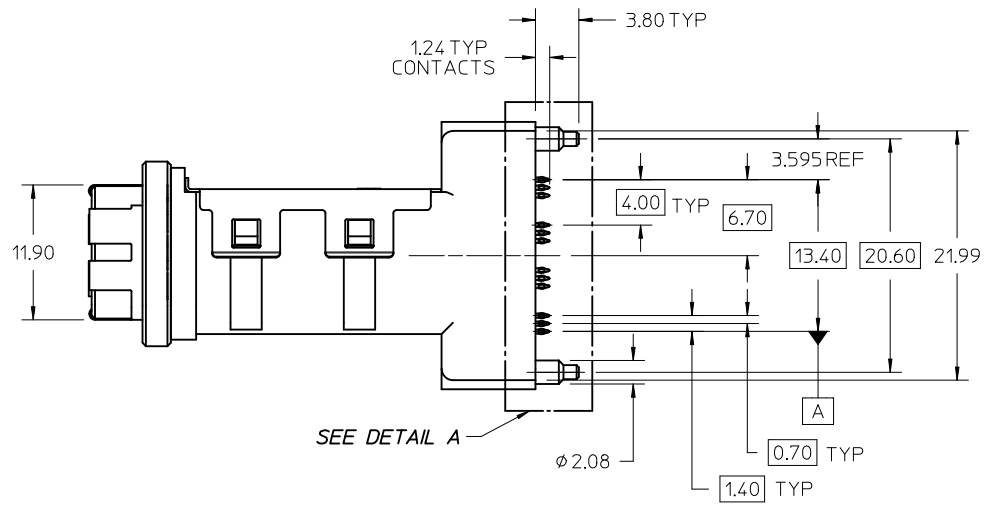
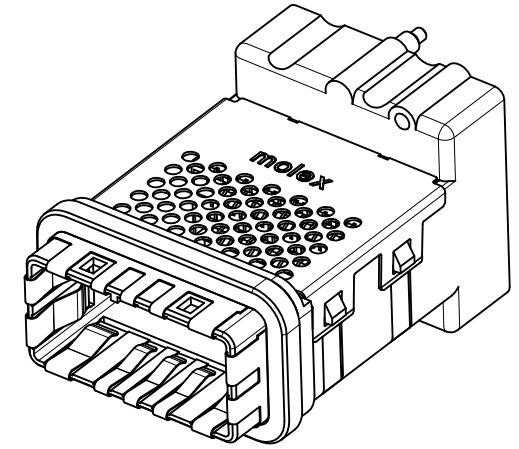


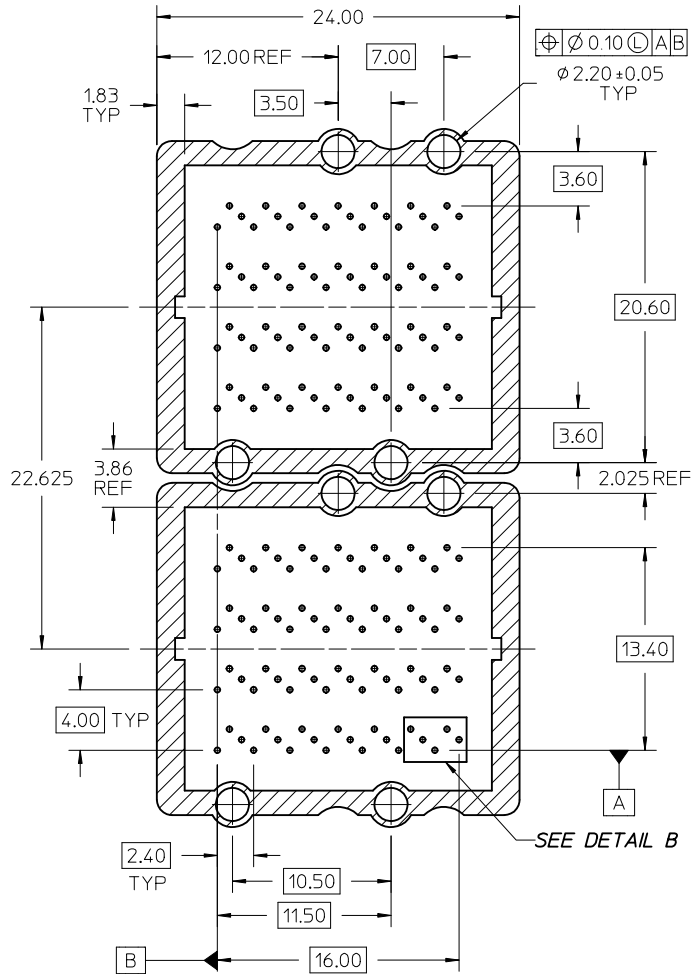
DETAIL A
SCALE 4:1



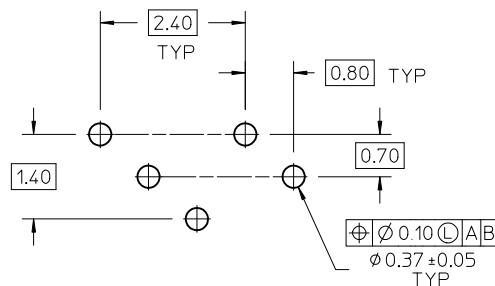
- NOTES:**
- MATERIALS:**
CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC, GLASS-FILLED, UL 94V-0
EMI HOUSING: NICKEL PLATED DIE CAST ALLOY
COVER: STAINLESS STEEL
HEATSINK BASE: ALUMINUM
EMI GASKET: CONDUCTIVE POLYMER
TERMINALS: COPPER ALLOY
 - PLATING:**
769970042 - CONTACT AREA: 0.764mm MIN. GOLD OVER 2.544mm MIN. NICKEL
TIN TAIL AREA: 0.764mm - 1.524mm TIN OVER 2.544mm MIN NICKEL
 - THIS CONNECTOR IS DESIGNED TO MATE WITH MOLEX IPASS CABLES.
 - PACKAGING SPECIFICATION: TRAY PACK PER PK-76997-001.
 - PRODUCT SPECIFICATION: PS-76997-001.
 - APPLICATION SPECIFICATION: AS-76997-001 AND AS-76997-002.

769970042	TIN
MATERIAL NUMBER	TAIL PLATING

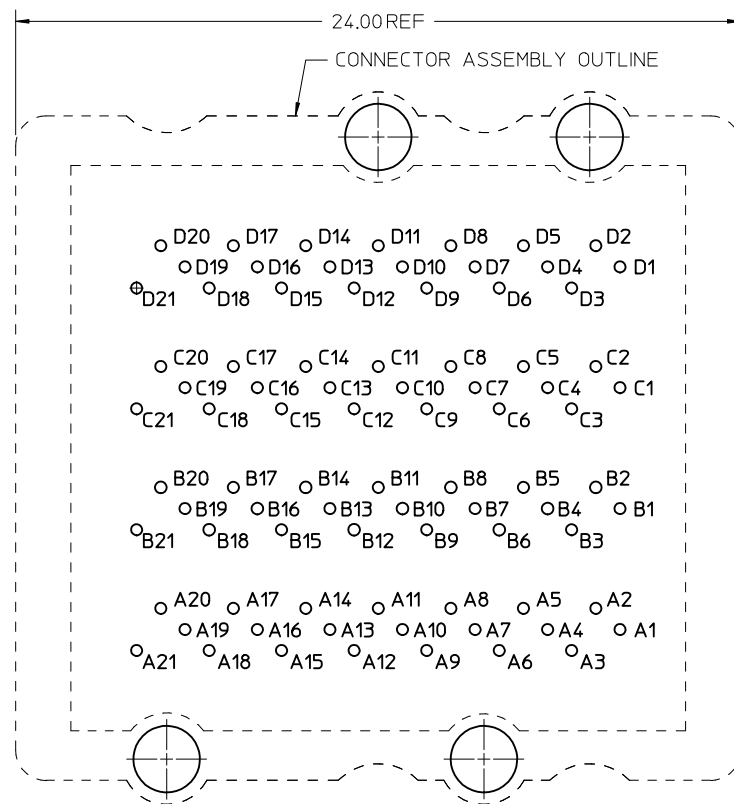
REVISED NOTE: SHT2 EC NO: UCP2011-0869 DRWN: LONG CHKD: APPR: MBANAKIS 2010/09/27 2010/10/12	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	mm INCH ± --- ± --- ± 0.25 ± --- ± --- ± ---	DRAWN BY JLONG	DATE 2010/02/12	CHECKED BY JLONG	DATE 2010/02/12	VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O			
		ANGULAR ± 1/2°		APPROVED BY MBANAKIS	DATE 2010/02/22	MOLEX INCORPORATED					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART				MATERIAL NO. SD-76997-005	DOCUMENT NO.	SHEET NO. 1 OF 3	



RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN
MULTIPLE APPLICATION SHOWN
ON MINIMUM PITCH
PCB THICKNESS: 1.57mm MIN.



DETAIL B
SCALE 16:1

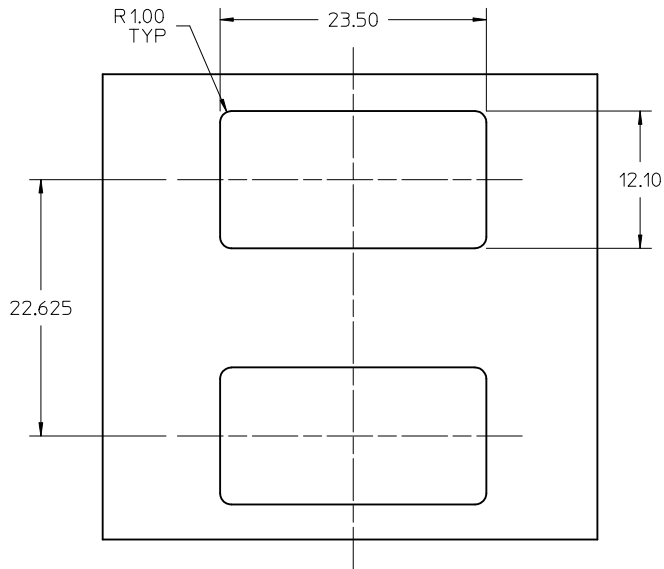
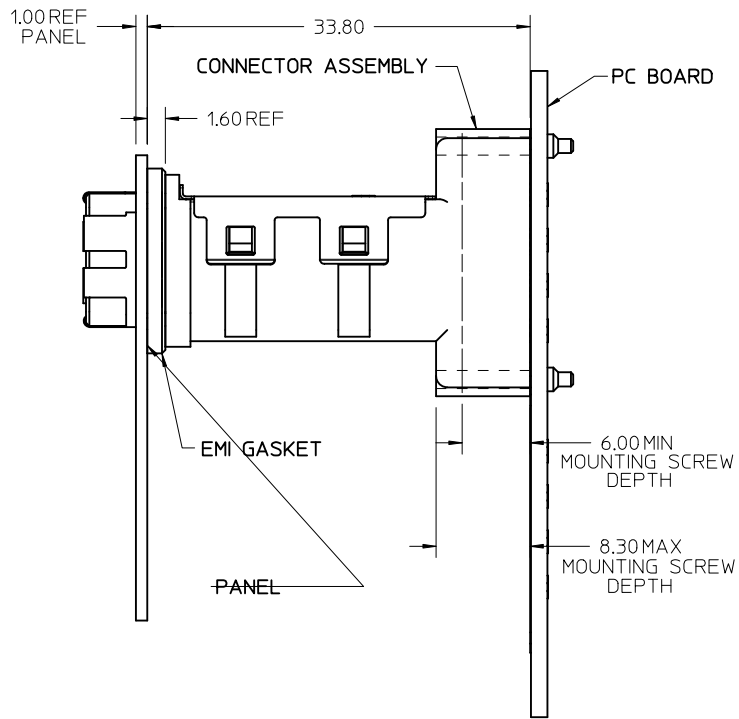


RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN

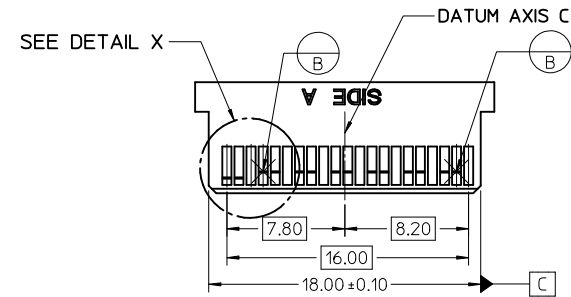
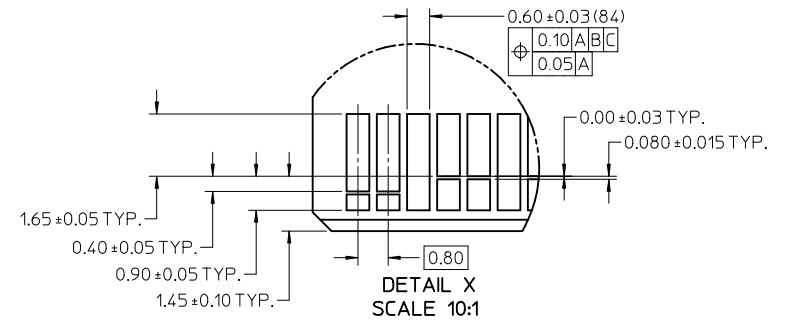
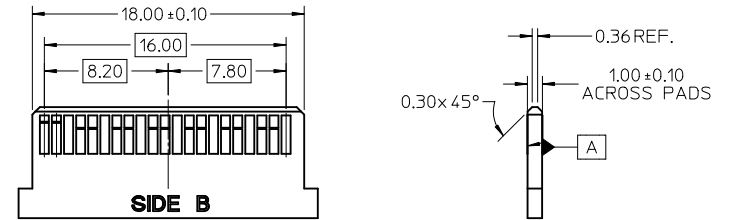
NOTES:

- CROSS-HATCHED AREA TO BE CONDUCTIVE ON THE PCB.
- CROSS-HATCHED AREA MUST BE INCORPORATED IN THE FLAT ROCK PRESS-FIT TOOLING.
- REFER TO THE PLATING DETAIL OF THE COMPLIANT PIN HOLES IN THE APPLICATION SPEC AS-76997-002 FOR THE DRILL SIZE AND ANNULAR RING FOR THE 0.37 \varnothing FINISHED HOLE.

SEE SHEET 1 EC NO: UCP2011-0869 DRAWN: LONG CHKD: APPR: MBANAKIS	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY JLONG	DATE 2010/02/12	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O	MOLEX INCORPORATED		
A1	DESCRIPTION REV	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	APPROVED BY MBANAKIS	DATE 2010/02/22	MATERIAL NO.	
		ANGULAR ± 1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		DOCUMENT NO. SD-76997-005	SHEET NO. 2 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



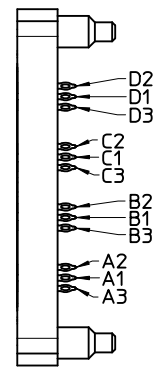
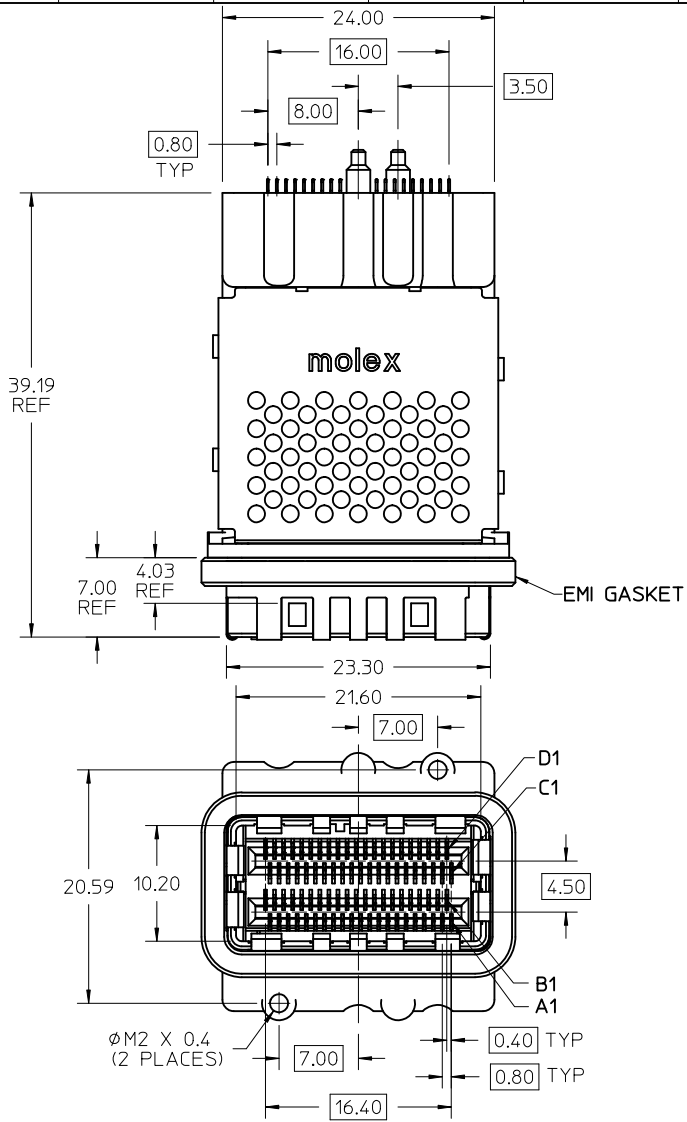
I/O PANEL CUT-OUT



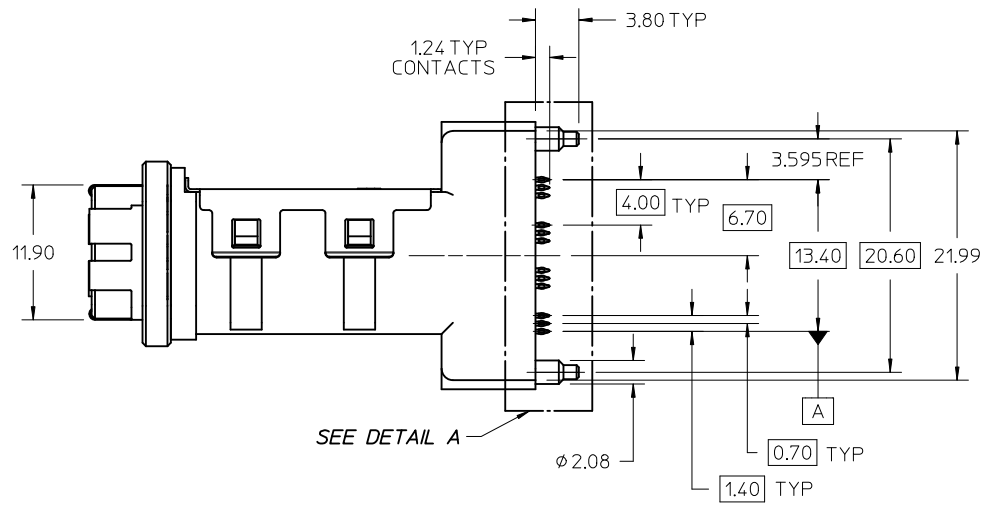
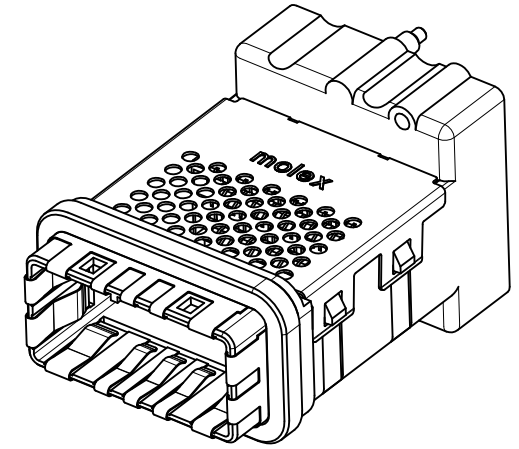
- NOTES:
- 0.03 MINIMUM KEEP OUT FOR SOLDER MASK AROUND ALL PADS
 - DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

RECOMMENDED PADDLE CARD LAYOUT

SEE SHEET 1 EC NO: UCP2011-0869 DRWN: JLONG CHKD: MBANAK I S APPR: MBANAK I S	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.25	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY	SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.25	± ---																			
1 PLACE	± ---	± ---																			
DESCRIPTION REV	DRAWN BY JLONG	DATE 2010/02/12	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O	MOLEX INCORPORATED	SHEET NO. 3 OF 3	A															
A1	APPROVED BY MBANAK I S	DATE 2010/02/22	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-76997-005	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	B															
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					C															

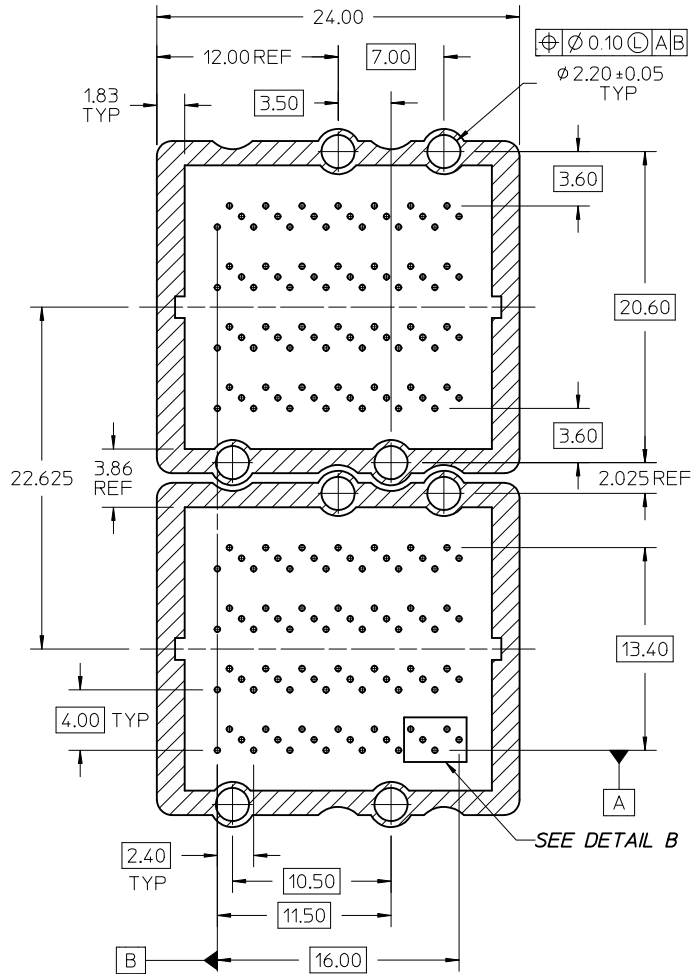


DETAIL A
SCALE 4:1

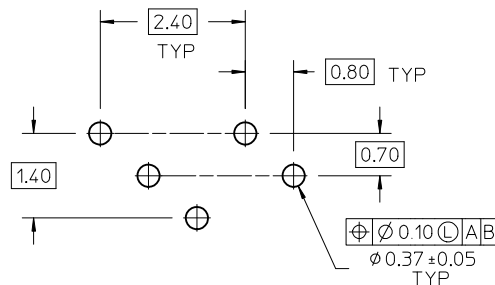


- NOTES:**
- MATERIALS:**
CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC, GLASS-FILLED, UL 94V-0
EMI HOUSING: NICKEL PLATED DIE CAST ALLOY
COVER: STAINLESS STEEL
HEATSINK BASE: ALUMINUM
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 - PLATING:**
769970042 - CONTACT AREA: 0.764mm MIN. GOLD OVER 2.544mm MIN. NICKEL
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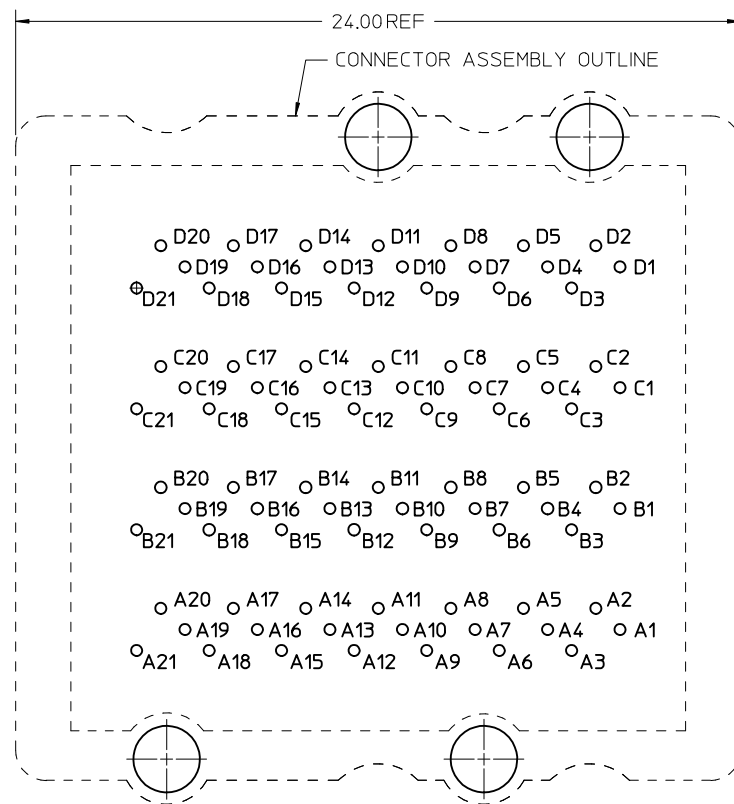
REVISED NOTE: SHT2 EC NO: UCP2011-0869 DRWN: LONG CHKD: APPR: MBANAKIS	DESCRIPTION 2010/09/27 2010/10/12	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY JLONG	DATE 2010/02/12	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O		
A1	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ANGULAR ±1/2°		APPROVED BY MBANAKIS		DATE 2010/02/22	MATERIAL NO. 769970042	
			SEE CHART		DOCUMENT NO. SD-76997-005		SHEET NO. 1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN
MULTIPLE APPLICATION SHOWN
ON MINIMUM PITCH
PCB THICKNESS: 1.57mm MIN.



DETAIL B
SCALE 16:1

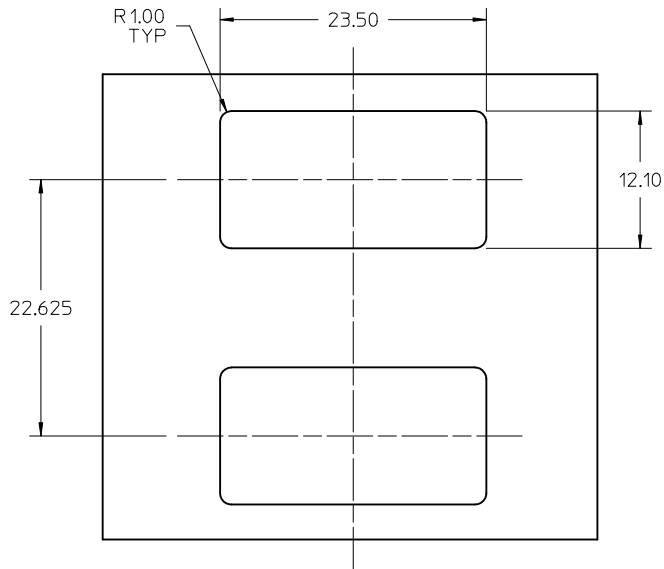
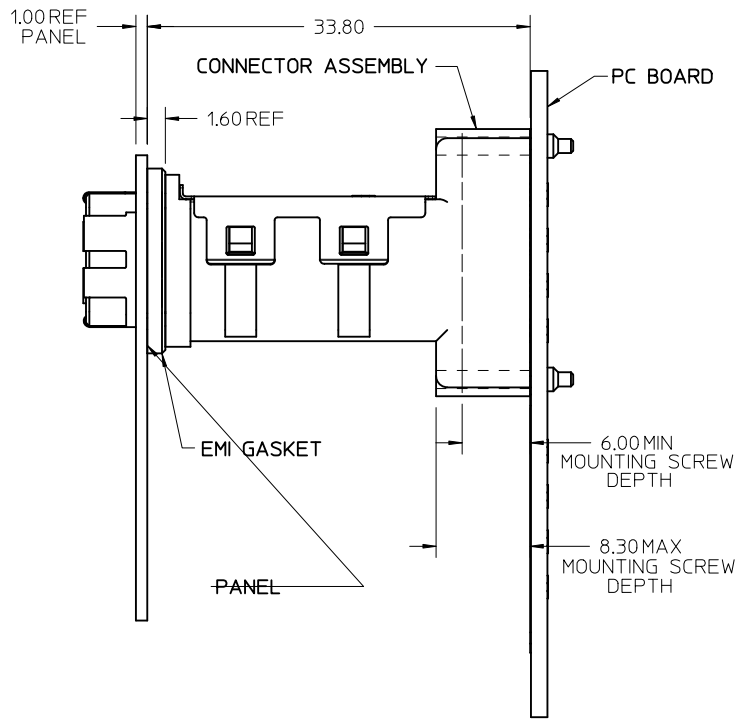


RECOMMENDED PCB LAYOUT
COMPONENT SIDE SHOWN

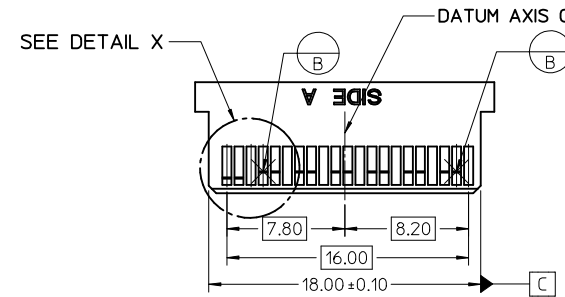
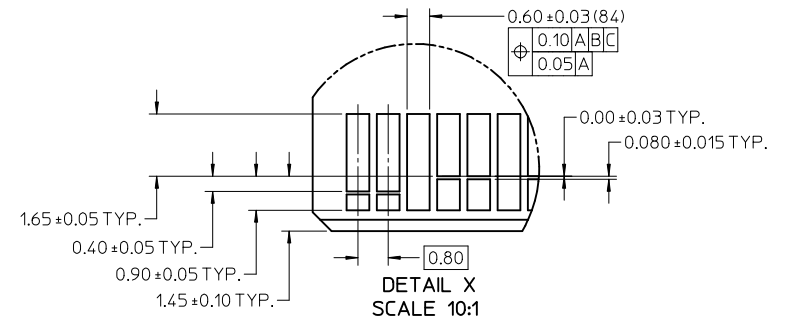
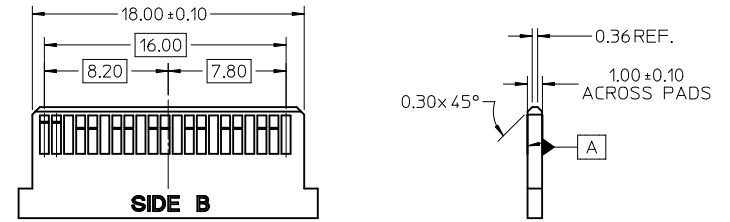
NOTES:

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SEE SHEET 1 EC NO: UCP2011-0869 DRAWN: LONG CHKD: APPR: MBANAKIS	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
		mm	INCH	DRAWN BY JLONG	DATE 2010/02/12	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O						
A1	DESCRIPTION REV	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	CHECKED BY JLONG	DATE 2010/02/12	APPROVED BY MBANAKIS	DATE 2010/02/22	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-76997-005	SHEET NO. 2 OF 3
		ANGULAR ± 1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



I/O PANEL CUT-OUT



- NOTES:
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 - DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

RECOMMENDED PADDLE CARD LAYOUT

SEE SHEET 1 EC NO: UCP2011-0869 DRWN: JLONG 2010/09/27 CHKD: MBANAK I S 2010/10/12 APPR: MBANAK I S	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	DRAWN BY JLONG	DATE 2010/02/12	TITLE VERTICAL CXP ASSEMBLY HIGH SPEED CHANNEL 0.8MM I/O			
		ANGULAR ± 1/2°				CHECKED BY JLONG	DATE 2010/02/12	APPROVED BY MBANAK I S			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MATERIAL NO.	DATE 2010/02/22	MOLEX INCORPORATED		DOCUMENT NO. SD-76997-005	SHEET NO. 3 OF 3